

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/09/2022

Details for "TLV341IDCKT"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
TLV341IDCKT	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DCK   6	2x1.3x0.9	7.6

\*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.034115	100	1000000	0.447462	4475
Sub-Total			0.034115	100	1000000	0.447462	4475
<b>Die Attach Adhesive</b>							
Other Inorganic Materials	Aluminum Oxide	1344-28-1	0.010608	30.000848	300008	0.139138	1391
Other Inorganic Materials	Silica	7631-86-9	0.001591	4.499562	44996	0.020868	209
Thermoplastics	Epoxy	85954-11-6	0.02316	65.49959	654996	0.303773	3038
Sub-Total			0.035359	100	1000000	0.463779	4638
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	3.415895	97.597	975970	44.803853	448039
Copper and Its Alloys	Iron	7439-89-6	0.07805	2.23	22300	1.023726	10237
Copper and Its Alloys	Phosphorus	7723-14-0	0.001225	0.035	350	0.016067	161
Zinc and Its Alloys	Zinc	7440-66-6	0.00483	0.138	1380	0.063352	634
Sub-Total			3.5	100	1000000	45.906998	459070
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	0.074289	95.120359	951204	0.974396	9744
Precious Metals	Gold	7440-57-5	0.000609	0.77977	7798	0.007988	80
Precious Metals	Palladium	7440-05-3	0.003202	4.099872	40999	0.041998	420
Sub-Total			0.0781	100	1000000	1.024382	10244
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	3.197832	86.999999	870000	41.943676	419437
Other Plastics and Rubber	Carbon Black	1333-86-4	0.003676	0.100009	1000	0.048215	482
Thermoplastics	Epoxy	85954-11-6	0.474161	12.899992	129000	6.219231	62192
Sub-Total			3.675669	100	1000000	48.211122	482111
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	0.300867	100	1000000	3.946257	39463
Sub-Total			0.300867	100	1000000	3.946257	39463
<b>Total</b>			7.62411			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/eoinfo](http://www.ti.com/eoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.